

Claims

1. A polishing apparatus comprising:
 - a plurality of polishing heads for holding a wafer,
 - a polishing pad for polishing the wafer,
 - a rotatable turn table having the polishing pad attached thereto,
 - a turn table driving mechanism for rotating the turn table,
 - a plurality of wafer-detecting sensors for detecting coming off of the wafer from the polishing head during polishing,
 - wherein the polishing apparatus has the wafer-detecting sensor disposed above peripheral portions of the respective polishing heads and on each downstream side in a rotation direction of the turn table with respect to the respective polishing heads,
 - wherein the turn table driving mechanism rotates the turn table directly by a motor without using a speed reducer and has a function of forcibly stopping a rotation of the motor.
2. The polishing apparatus according to claim 1, wherein the polishing apparatus also has the wafer-detecting sensor disposed above peripheral portions of the respective polishing heads and on each upstream side in a rotation direction of the turn table with respect to the respective polishing heads.
3. The polishing apparatus according to claim 1 or claim 2, wherein the wafer-detecting sensors takes 80 μ s

or less to output a detection signal from detecting the wafer.